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CONFIRMATION NO. 1863

SERIAL NUMBER	FILING or 371(c) DATE	CLASS	GROUP ART UNIT	ATTORNEY DOCKET NO.
10/765,931	01/29/2004 RULE	-220- 438	2823	Q79041

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None /KII/

** CONTINUING DATA *****

** FOREIGN APPLICATIONS ***** Yes /KN/
 JAPAN 2003-110125 04/15/2003

** IF REQUIRED, FOREIGN FILING LICENSE GRANTED **
 06/12/2004

Foreign Priority claimed	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No	<input type="checkbox"/> Met after Allowance /KN/ Initials	STATE OR COUNTRY	SHEETS DRAWINGS	TOTAL CLAIMS	INDEPENDENT CLAIMS
35 USC 119(a-d) conditions met	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No		JAPAN	2	15 7	3 2

ADDRESS

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TITLE

Solder deposition method and solder bump forming method

FILING FEE RECEIVED 1640	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:	<input type="checkbox"/> All Fees
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